

General Purpose Transistor

NPN Silicon

- Moisture Sensitivity Level: 1
- ESD Rating: Human Body Model: >4000 V
Machine Model: >400 V
- This is a Pb-Free Device

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	65	Vdc
Collector-Base Voltage	V_{CBO}	80	Vdc
Emitter-Base Voltage	V_{EBO}	6.0	Vdc
Collector Current – Continuous	I_C	100	mAdc

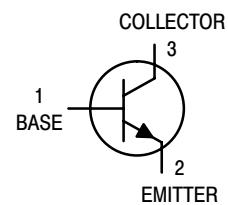
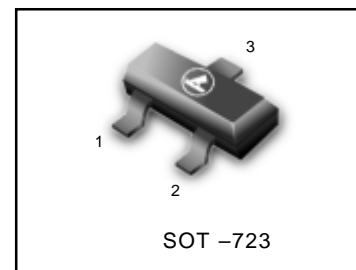
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	265 2.1	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	470	$^\circ\text{C/W}$
Total Device Dissipation Alumina Substrate (Note 2) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	640 5.1	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction to Ambient (Note 2)	$R_{\theta JA}$	195	$^\circ\text{C/W}$
Junction and Storage	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.

LBC846BM3T5G



ORDERING INFORMATION

Device	Marking	Shipping
LBC846BM3T5G	1B	3000/Tape & Reel

LBC846BM3T5G

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage ($I_C = 10 \text{ mA}$)	$V_{(\text{BR})\text{CEO}}$	65	–	–	V
Collector–Emitter Breakdown Voltage ($I_C = 10 \mu\text{A}$, $V_{EB} = 0$)	$V_{(\text{BR})\text{CES}}$	80	–	–	V
Collector–Base Breakdown Voltage ($I_C = 10 \mu\text{A}$)	$V_{(\text{BR})\text{CBO}}$	80	–	–	V
Emitter–Base Breakdown Voltage ($I_E = 1.0 \mu\text{A}$)	$V_{(\text{BR})\text{EBO}}$	6.0	–	–	V
Collector Cutoff Current ($V_{CB} = 30 \text{ V}$) ($V_{CB} = 30 \text{ V}$, $T_A = 150^\circ\text{C}$)	I_{CBO}	– –	– –	15 5.0	nA μA

ON CHARACTERISTICS

DC Current Gain ($I_C = 10 \mu\text{A}$, $V_{CE} = 5.0 \text{ V}$) ($I_C = 2.0 \text{ mA}$, $V_{CE} = 5.0 \text{ V}$)	h_{FE}	– 200	150 290	– 450	–
Collector–Emitter Saturation Voltage ($I_C = 10 \text{ mA}$, $I_B = 0.5 \text{ mA}$) ($I_C = 100 \text{ mA}$, $I_B = 5.0 \text{ mA}$)	$V_{CE(\text{sat})}$	– –	– –	0.25 0.6	V
Base–Emitter Saturation Voltage ($I_C = 10 \text{ mA}$, $I_B = 0.5 \text{ mA}$) ($I_C = 100 \text{ mA}$, $I_B = 5.0 \text{ mA}$)	$V_{BE(\text{sat})}$	– –	0.7 0.9	– –	V
Base–Emitter Voltage ($I_C = 2.0 \text{ mA}$, $V_{CE} = 5.0 \text{ V}$) ($I_C = 10 \text{ mA}$, $V_{CE} = 5.0 \text{ V}$)	$V_{BE(\text{on})}$	580 –	660 –	700 770	mV

SMALL-SIGNAL CHARACTERISTICS

Current–Gain – Bandwidth Product ($I_C = 10 \text{ mA}$, $V_{CE} = 5.0 \text{ Vdc}$, $f = 100 \text{ MHz}$)	f_T	100	–	–	MHz
Output Capacitance ($V_{CB} = 10 \text{ V}$, $f = 1.0 \text{ MHz}$)	C_{obo}	–	–	4.5	pF
Noise Figure ($I_C = 0.2 \text{ mA}$, $V_{CE} = 5.0 \text{ Vdc}$, $R_S = 2.0 \text{ k}\Omega$, $f = 1.0 \text{ kHz}$, $BW = 200 \text{ Hz}$)	NF	–	–	10	dB

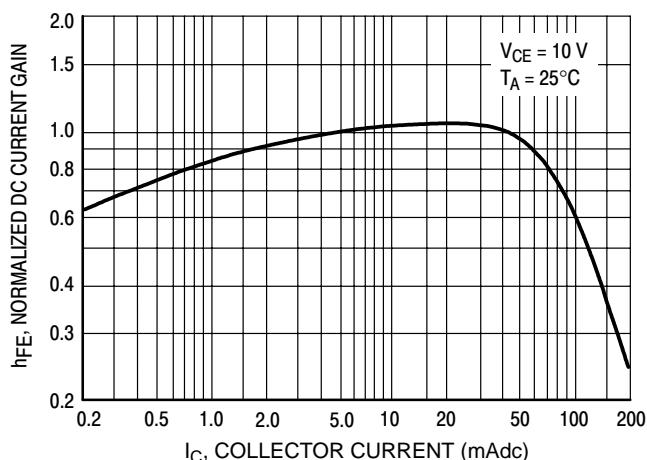


Figure 1. Normalized DC Current Gain

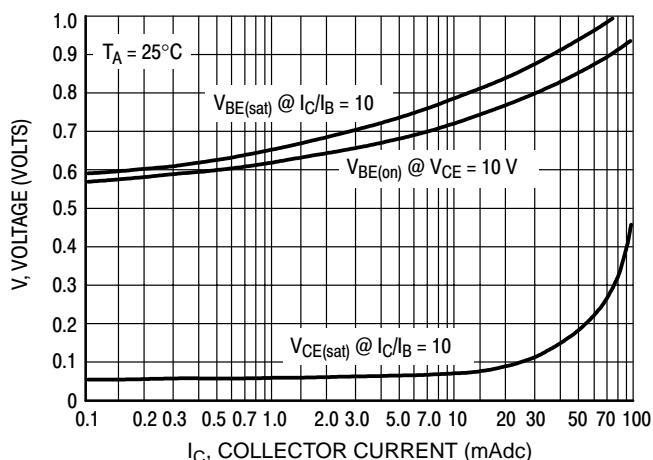


Figure 2. "Saturation" and "On" Voltages

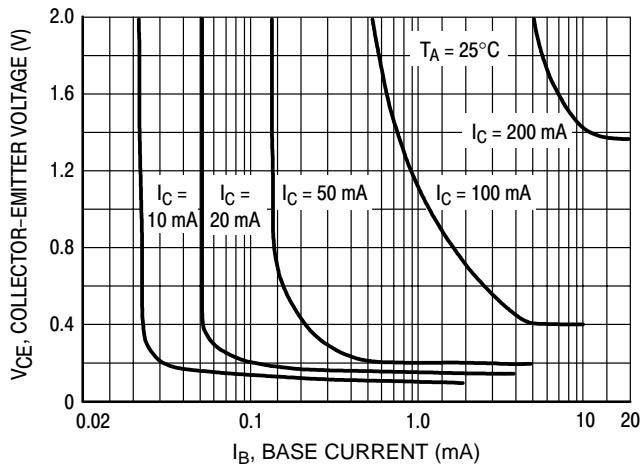


Figure 3. Collector Saturation Region

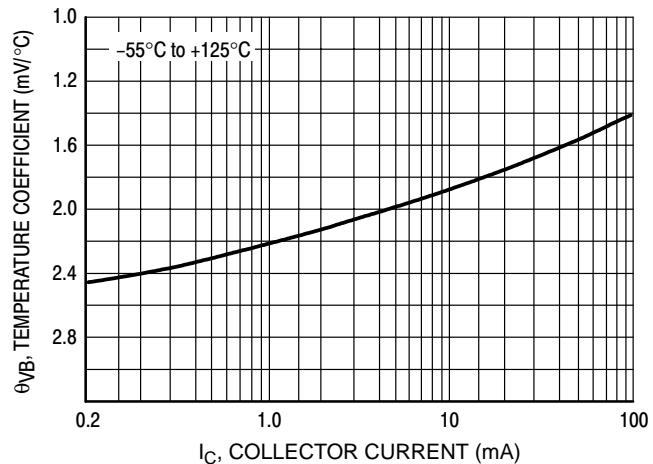


Figure 4. Base-Emitter Temperature Coefficient

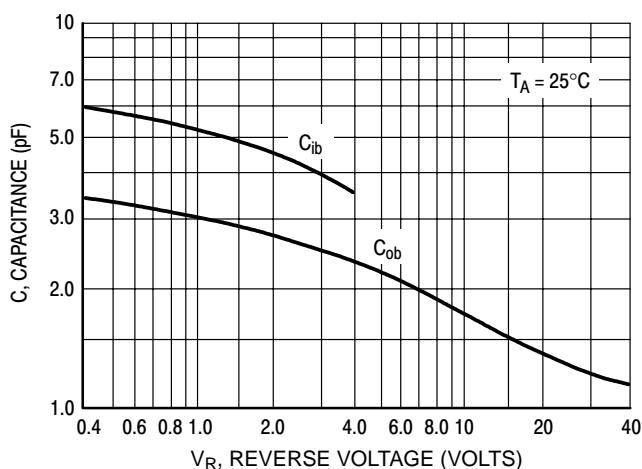


Figure 5. Capacitances

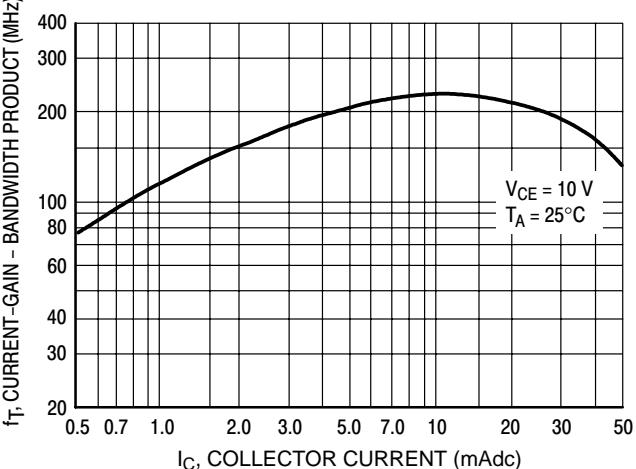
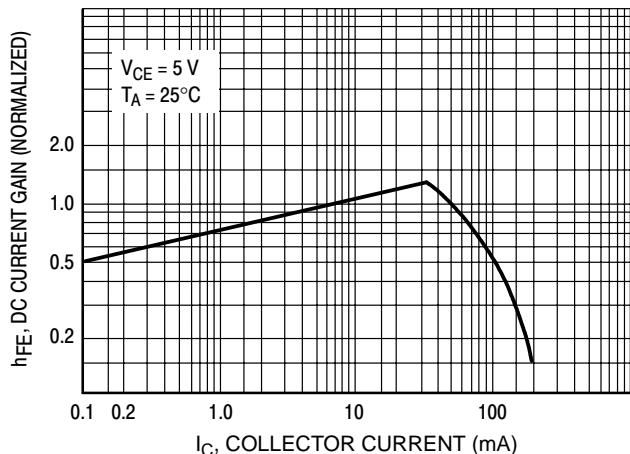
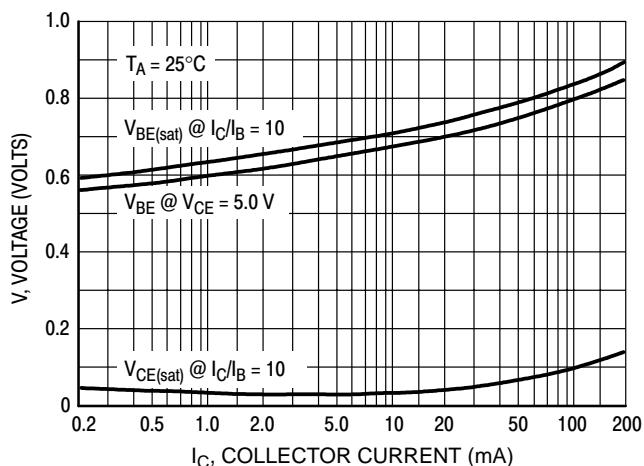
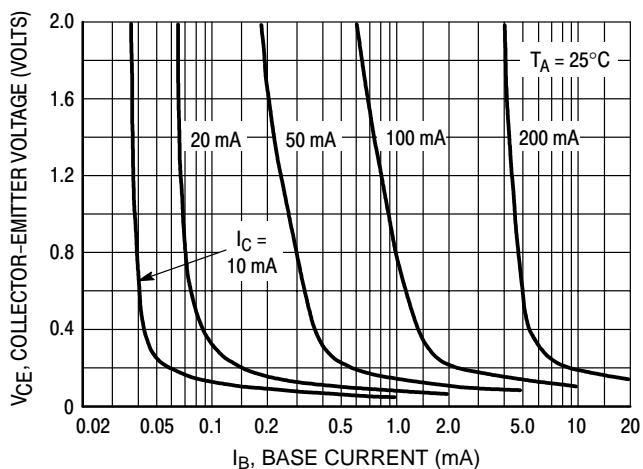
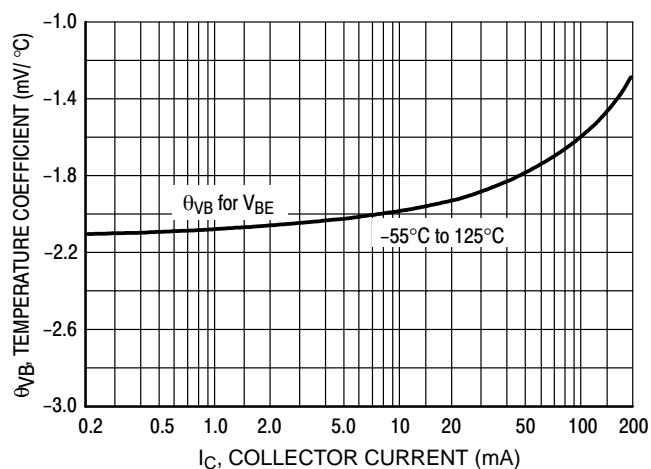
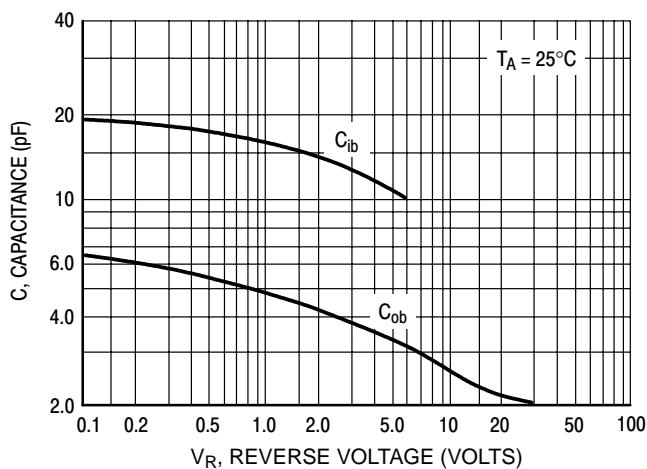
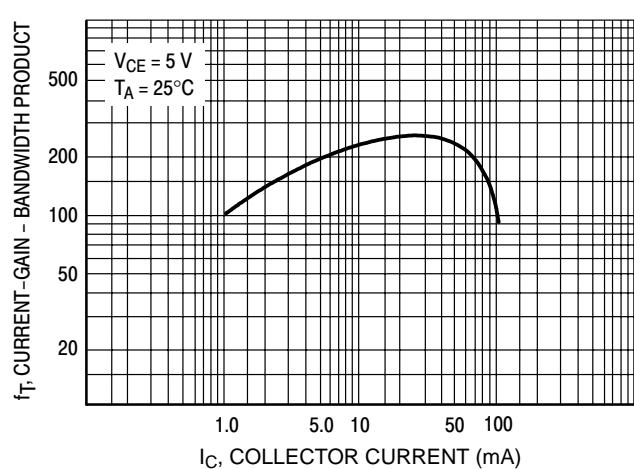
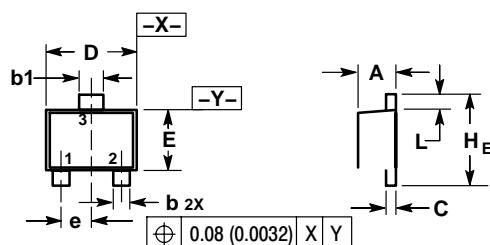


Figure 6. Current-Gain – Bandwidth Product

LBC846BM3T5G

Figure 7. DC Current Gain

Figure 8. "On" Voltage

Figure 9. Collector Saturation Region

Figure 10. Base-Emitter Temperature Coefficient

Figure 11. Capacitance

Figure 12. Current-Gain – Bandwidth Product

LBC846BM3T5G
SOT-723


STYLE 1:
PIN 1. BASE
2. Emitter
3. Collector

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.022
b	0.15	0.21	0.27	0.0059	0.0083	0.0106
b1	0.25	0.31	0.37	0.010	0.012	0.015
C	0.07	0.12	0.17	0.0028	0.0047	0.0067
D	1.15	1.20	1.25	0.045	0.047	0.049
E	0.75	0.80	0.85	0.03	0.032	0.034
e	0.40 BSC			0.016 BSC		
H _E	1.15	1.20	1.25	0.045	0.047	0.049
L	0.15	0.20	0.25	0.0059	0.0079	0.0098

SOLDERING FOOTPRINT*
